



ALPHA & OMEGA
SEMICONDUCTOR

AOC3868

12V Common-Drain Dual N-Channel MOSFET

General Description

- Trench Power MOSFET technology
- Low $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS and Halogen-Free Compliant

Product Summary

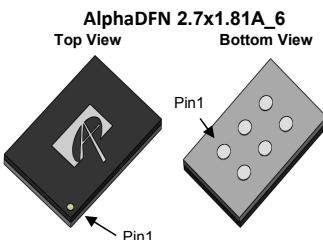
V_{SS}	12V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$)	< 5mΩ
$R_{SS(ON)}$ (at $V_{GS}=4.0V$)	< 5.3mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.7V$)	< 5.5mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$)	< 6mΩ
$R_{SS(ON)}$ (at $V_{GS}=2.5V$)	< 7mΩ

Applications

- Battery protection switch
- Mobile device battery charging and discharging

Typical ESD protection

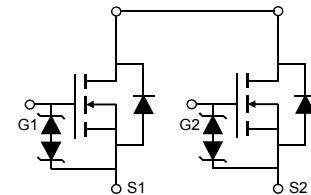
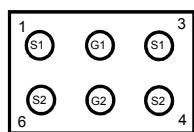
HBM Class 3A



Top View



Bottom View



Orderable Part Number

AOC3868

Package Type

AlphaDFN 2.7x1.81A_6

Form

Tape & Reel

Minimum Order Quantity

5000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	V_{SS}	12	V
Gate-Source Voltage	V_{GS}	± 8	V
Source Current(DC) ^{Note1}	I_S $T_A=25^\circ\text{C}$	20	A
Source Current(Pulse) ^{Note2}	I_{SM}	80	
Power Dissipation ^{Note1}	P_D $T_A=25^\circ\text{C}$	2.5	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient	$t \leq 10\text{s}$	40	°C/W
Maximum Junction-to-Ambient	Steady-State	50	°C/W

Note 1. I_S rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

Note 2. PW <10 μs pulses, duty cycle 1% max.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
STATIC PARAMETERS							
BV_{SSS}	Source-Source Breakdown Voltage	$I_S=250\mu\text{A}, V_{GS}=0\text{V}$	Test Circuit 6	12		V	
I_{SSS}	Zero Gate Voltage Source Current	$V_{SS}=12\text{V}, V_{GS}=0\text{V}$	Test Circuit 1		1	μA	
			$T_J=55^\circ\text{C}$		5		
I_{GSS}	Gate leakage current	$V_{SS}=0\text{V}, V_{GS}=\pm 8\text{V}$	Test Circuit 2		± 10	μA	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{SS}=V_{GS}, I_S=250\mu\text{A}$	Test Circuit 3	0.4	0.72	1.1	V
$R_{SS(\text{ON})}$	Static Source to Source On-Resistance	$V_{GS}=4.5\text{V}, I_S=4\text{A}$	Test Circuit 4	2.9	4.15	5.0	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		3.8	5.5	6.6	
		$V_{GS}=4.0\text{V}, I_S=4\text{A}$	Test Circuit 4	3.0	4.25	5.3	$\text{m}\Omega$
		$V_{GS}=3.7\text{V}, I_S=4\text{A}$	Test Circuit 4	3.1	4.35	5.5	$\text{m}\Omega$
		$V_{GS}=3.1\text{V}, I_S=4\text{A}$	Test Circuit 4	3.2	4.6	6.0	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{SS}=5\text{V}, I_S=4\text{A}$	Test Circuit 4	3.5	5.1	7.0	$\text{m}\Omega$
			Test Circuit 3		50		
V_{FSS}	Forward Source to Source Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	Test Circuit 5		0.59	1	V
DYNAMIC PARAMETERS							
R_g	Gate resistance	$f=1\text{MHz}$			1.2	$\text{k}\Omega$	
SWITCHING PARAMETERS							
Q_g	Total Gate Charge	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, I_S=4\text{A}$			35	50	nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, R_L=1.5\Omega,$ $R_{\text{GEN}}=3\Omega$	Test Circuit 8		1.2		μs
t_r	Turn-On Rise Time				3		μs
$t_{D(\text{off})}$	Turn-Off DelayTime				5.5		μs
t_f	Turn-Off Fall Time				9.5		μs

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

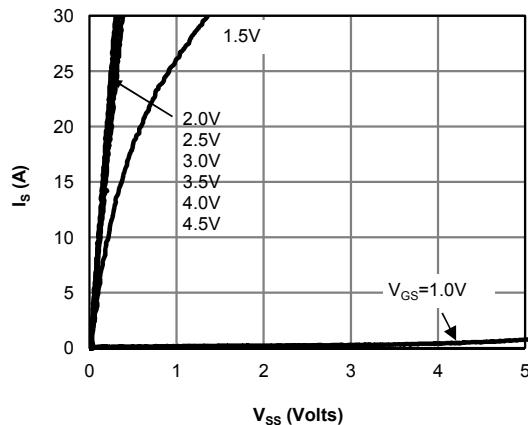


Figure 1: On-Region Characteristics

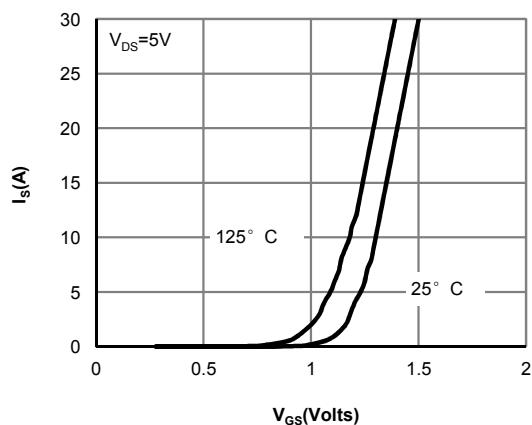


Figure 2: Transfer Characteristics

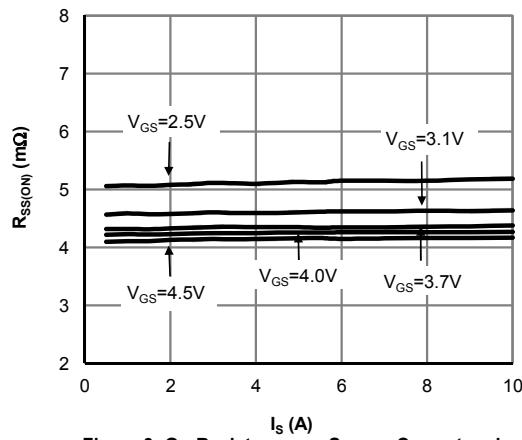


Figure 3: On-Resistance vs. Source Current and Gate Voltage

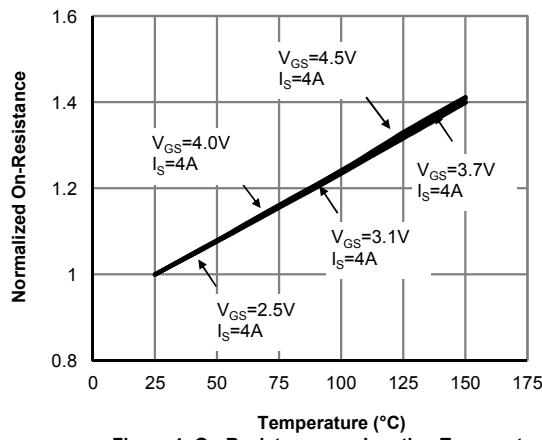


Figure 4: On-Resistance vs. Junction Temperature

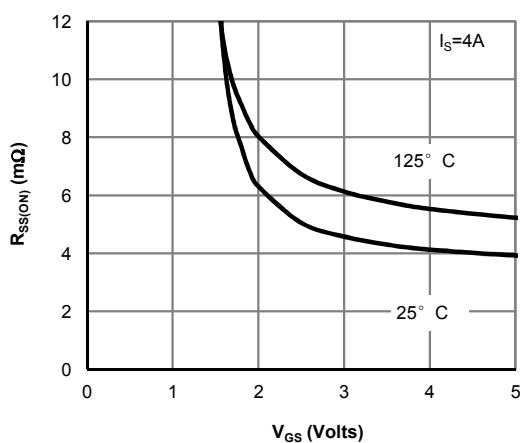


Figure 5: On-Resistance vs. Gate-Source Voltage

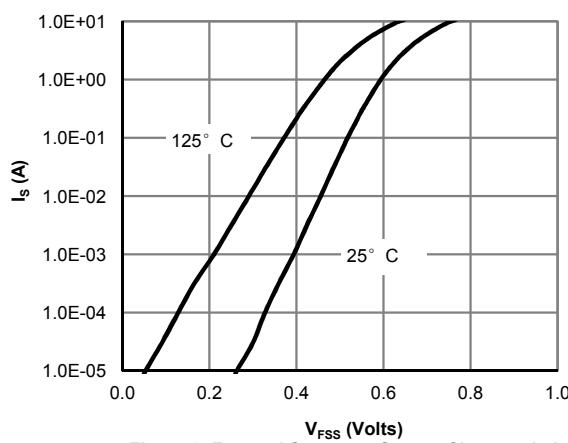


Figure 6: Forward Source to Source Characteristics



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

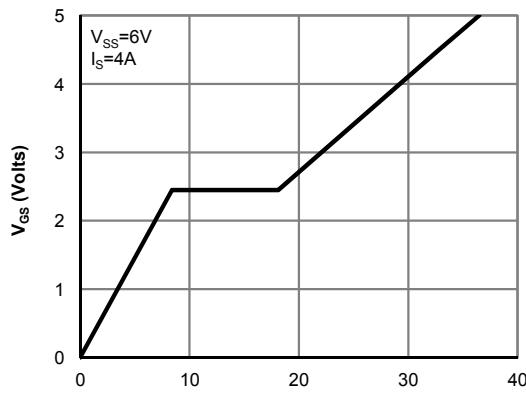


Figure 7: Gate-Charge Characteristics

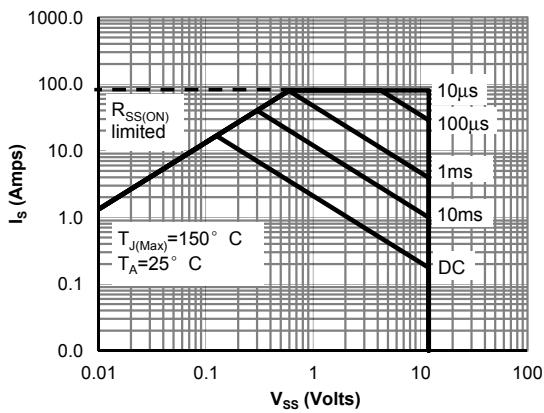


Figure 8: Maximum Forward Biased Safe Operating Area (Note1)

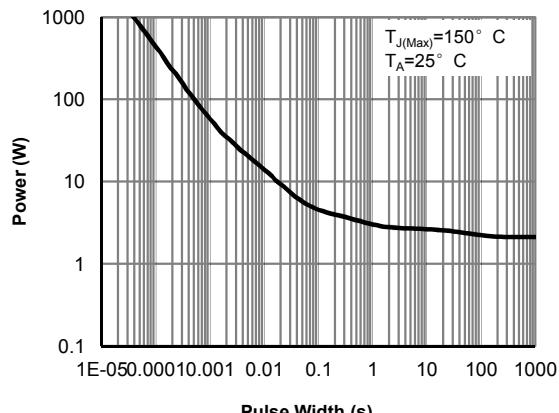


Figure 9: Single Pulse Power Rating Junction-to-Ambient (Note1)

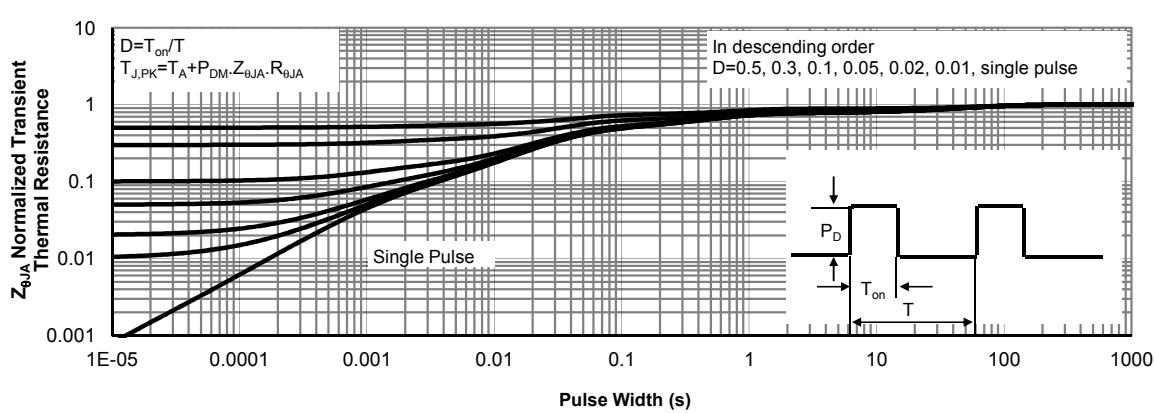
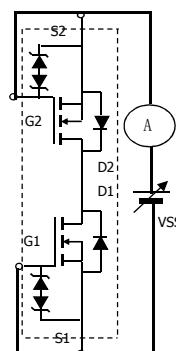


Figure 10: Normalized Maximum Transient Thermal Impedance (Note1)

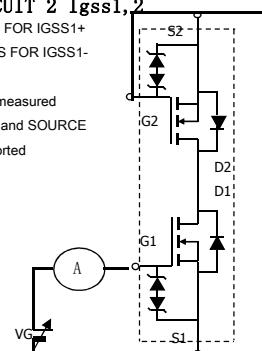


TEST CIRCUIT 1 Isss
POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-



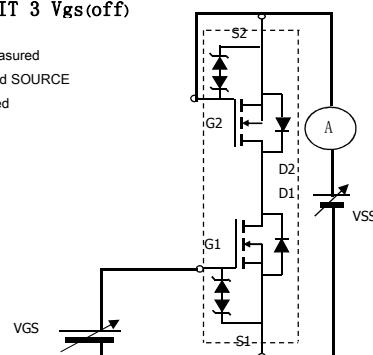
TEST CIRCUIT 2 Igss1,2
POSITIVE VGS FOR IGSS1+
NEGATIVE VGS FOR IGSS1-

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted



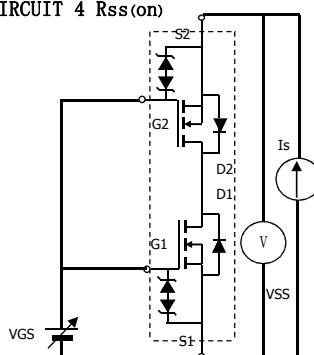
TEST CIRCUIT 3 Vgs(off)

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted



TEST CIRCUIT 4 Rss(on)

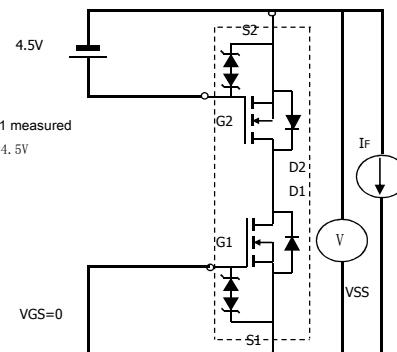
Vss/Is



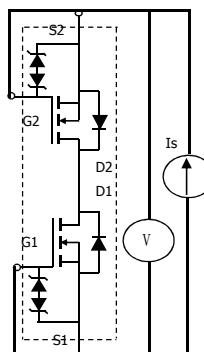
TEST CIRCUIT 5 VF(ss)1,2

When FET1 measured
FET2 VGS=4.5V

VGS=0

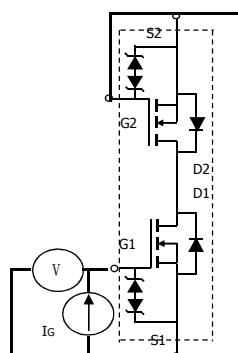


TEST CIRCUIT 6 BVdss
POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-



TEST CIRCUIT 7 BVgs01,2
POSITIVE VSS FOR ISSS+
NEGATIVE VSS FOR ISSS-

When FET1 is measured
between GATE and SOURCE
of FET2 are shorted



TEST CIRCUIT 8
Switching time

